Model JFP PP5-5 SERIES

EUTECTIC DIE BONDER

APPLICATIONS:

Pick & Place
Flip Chip assembly
Very small and large component
MEMS,MMICS, IR sensor, Opto, Laser diode…
Thermo-sonic die bonding
Reflow, thermal cycle
Eutectic thermo cycle
Wafer sorter up to 8″
Dispenser for epoxy & solder paste
Stamping

The JFP PP5 is most versatile semi automatic Pick & Place platform. It can be used in a wide field of applications such as; ASIC; MMIC; MEMS; VECEL....
It achieves maximum accuracy placement using high quality optical device with a placement @ **< 3 µm @ 3 sigma.**
The PP5 series provide customers with the best cost / performance system on the market

Our proven expertise in bonding application effectively provides the technology and support to help our customers. A robust, and reliable mechanical concept, designed to be external vibration free. The PP5 is user friendly, flexible and requires minimal training to operate.

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Specifications	
Model:	Pick & Place / Eutectic Die Bonder PP5-5
Motorized Tables:	X 250mm, Y 100mm / 1μm Manual Theta Joystick control: 2 speeds, adjustable
Pick & Place Head	Motorized Z Vavuum picking tool, 1/8 Minimum force: 10gr
Die size:	Minimum200*200 μm Minimum25*25 mm
Substrate handled:	Up to 300x500 mm
Eutectic:	Digital temperature profile control / 3 set points 2 inches workholder with nitrogen enclosure 450C eutectic pulse 350C continue
Vision:	CCD Color camera HR 17'' TFT panel Optical zoom 20X to 150X adjustable Target Crosshair generator
Light:	Direct and pen light, LED ring
Alignment:	Place Mode direct for flip application 2 Ref point / Indexed XY at P&P position
Parameters:	LCD screen Force: 3 ranges programmable 10gr to 6Kgr Bond Time: 1ms to 10sec programmable Scrub: XY amplitude and cycle programmable
Vacuum:	Selectable
Matrix:	Mapping / step and repeat / 2 ref point / Indexed
Utilities	100Vac to 230Vac / 500W Vacuum: 70%

Options

- Automated sequence , process storage capability, PC driven option
- Heated Work-Holder up to 8 inches (200mm)
- Double micro jet hot gaz
- Rework BGA & Flip chip with solder removal module
- Oven C4 compatible
- Ultrasonic Flip : High Power Digital Ultrasonic generator
- Transducer: Heavy duty 60Khz transducer
- Heavy duty bond head, 3 ranges Programmable up to 15Kg
- Piezzo driven micro gripper pick up head
- Dispenser
- Stamping
- UV insulator

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